

**AMENDMENTS TO THE SPECIFICATION**

Please delete the section heading beginning at page 5, line 17.

Please replace the paragraph beginning at page 6, line 5, with the following rewritten paragraph:

-- It is another object of the present invention to provide a plating-pretreatment solution capable of inhibiting the occurrence of migration of metals such as copper and a method using the plating-pretreatment solution. --

Please replace the paragraph beginning at page 7, line 12, with the following rewritten paragraph:

-- Fig. 1 is a view showing a test piece having an anode and cathode alternate layout pattern (hereinafter ~~refer~~ referred to as comb shaped pattern electrodes), which is used to show effects ascribed to the treatment with the plating-pretreatment solution of the present invention. --

Please delete the paragraph beginning at page 8, line 1.

Please delete the paragraph beginning at page 8, line 5.

Please delete the section heading beginning at page 21, line 16.

Please replace the paragraph beginning at page 24, line 1 with the following rewritten paragraph:

-- S'PER FLEX (trade name, available from Sumitomo Metal Mining Co., Ltd.), which had been obtained by sputtering a Ni-Cr alloy layer consisting of 7% by weight of Cr and 93% by weight of Ni in a thickness of 70 Å, then plating the layer with Cu by electroless plating and then further plating it with Cu by electroplating in a thickness of 8 µm, was coated with a photoresist, and then the photoresist was subjected to exposure and alkali development. Then, using a cupric chloride solution, comb shaped pattern electrodes designated generally by reference numeral 10 of 50 µm pitch were formed by etching as shown in Fig. 1 to prepare three test pieces. The opposite teeth length of the comb shaped pattern electrodes 10 was 10 mm. The positive electrode had 8 teeth, and the negative electrode had 8 teeth. --